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# **Body Style:** Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.0100 **Terminal Length:** Between 0.005 inches and 0.020 inches **Body Length:** 0.055 inches **Body Width:** 0.055 inches **Body Height:** Between 0.020 inches and 0.057 inches Schematic Diagram Designator: No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp: 100000.0 megohms **Capacitance Value Per Section:** 33.000 picofarads single section Nonderated Operating Temp: Between -55.0 degrees celsius and 125.0 degrees celsius Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius: 90.0 single section Nonderated Continuous Voltage Rating And Type Per Section: 50.0 dc single section **Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:** -20.0/+20.0 single section **Tolerance Range Per Section:** -1.00/+1.00 percent single section **Case Material:** Ceramic or glass Insulation Resistance At Reference Temp: 1000000.0 megohms **Dissipation Factor At Reference Tempurature In Percent:** 0.0500 **Quality Factor At Reference Temp:** 100000.0000 **Terminal Surface Treatment:** Solder **Test Data Document:** 81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification

format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data in specification environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).



### Terminal Type And Quantity:

2 bonding pad

#### Specification Data:

81349-mil-c-55681/4 government specification

Shelf Life:

N/a

## Unit Of Measure:

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# Demilitarization:

No

Fiig:

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